### PROFESSIONAL EXPERIENCE

### Power Electronics Research Intern,

U of T Lab for Advanced Power Conversion and Systems Analysis May 2024 – present | Toronto, ON, Canada

- Developed *LTspice* simulations of high-speed gate drivers for emerging 1200V eGaN HEMTs in VFDs to guide the selection of components (diodes, filters) and parameters (dead time, fsw).
- Created the PCB schematic, BOM, libraries, DFM/DFT rules, layout, and routing of a 700VDC half-bridge containing bottom-cooled GaN devices, level-shifted bootstrap driver circuits, and DC link capacitors using Altium Designer, mitigating inductance of commutation and gate loops, Miller plateau, creepage, and EMI.
- Verified IPC-2221 compliance and extracted worst-case conduction and switching losses to evaluate and select RC snubbers, thermal via patterns, TIMs, and heatsinks to avoid thermal runaway.
- SMT-soldered the four-layer board, programmed a DSP via *PLECS* to send high-resolution SPWM gating signals and read Hall sensor mixed signals, and analyzed oscilloscope and DMM readings.

#### RTL Design Engineering Intern,

Intel Corporation — Programmable Solutions Group May 2023 - Apr 2024 | San Jose, CA, United States

- Explored microarchitectural logic design, interfacing (AXI4, JTAG, UART), timing, benchmarking, simulation, and verification of Nios V, Intel's RISC-V based embedded processor IP family for FPGAs.
- Optimized instruction pipelining via register balancing, controlbased logic reuse, and FPGA primitive instantiation, improving area usage by 20%, fmax by 20%, and instructions per cycle by 5%.
- Redesigned the hardware for RISC-V based external debug support and validated it using Quartus Prime, C, QuestaSim, OpenOCD, and gdb, improving area utilization by 10% and latency by a factor of 6.
- Defined a custom SystemVerilog style guide to improve code readability, authored numerous functional specifications, analyzed trends in MS Excel, and enhanced customer-facing documentation.

# Field Robotics Research Intern,

UTIAS Autonomous Space Robotics Lab May 2022 – Aug 2022 | Mississauga, ON, Canada

- Planned, conducted, and documented field tests at various lakes to validate SLAM and stochastic navigation of a retrofitted (wiring harnesses and 3D-printed brackets for extra hardware) ASV.
- Created a *Python* pipeline to extract and filter lake geometries from datasets, generate satellite-informed water masks and graph instances, and execute and evaluate route-planning algorithms.
- Designed a GUI using ROS and ReactJS to track the robot and visualize its navigation policy in real time over a wireless network.
- Y. Huang, H. Dugmag, T.D. Barfoot, F. Shkurti, "Stochastic Planning for ASV Navigation Using Satellite Images", 2023 IEEE International Conference on Robotics and Automation (ICRA). ☑

## Machine Learning Research Intern, U of T Forcolab Group May 2021 – Aug 2021 | Toronto, ON, Canada

- Conducted a literature review analyzing the potential of using collaborative Stack Overflow posts to organize information for improved searching and learning experiences.
- Investigated various code clone detection models, including BERTbased language models, to compare educational code snippets to official programming language documentation.
- Optimized parameters for hierarchical density-based clustering of Stack Overflow posts using Python (NumPy, Pandas, PyPlot) and Docker, increasing precision by 11%.

### **SKILLS**

Design: Altium Designer, LTspice, PLECS, Cadence Virtuoso, MATLAB, Simulink, Fusion 360, SolidWorks, Amateur Radio **Lab:** Oscilloscope, VNA, Function Generator, Power Analyzer, Bench Supply, Spectrum Analyzer, Logic Analyzer, DMM, SMT/TH Soldering, 3D Printing, Laser Cutting, Woodworking **Embedded:** Python, C, C++, SystemVerilog, VCS, QuestaSim, Assembly, FPGA, DSP, Arduino, Raspberry Pi, Git, Docker, ROS

#### **EDUCATION**

B.A.Sc. in Engineering Science (Major in Electrical and Computer Engineering), University of Toronto (St. George) Sep 2020 – May 2025 | Toronto, ON, Canada

- PEY Co-op, Certificate in Electric Vehicle Design, Certificate in Engineering Business.
- 3.96 cGPA, 92% avg., 6/6 Dean's Honour List, 11 meritbased competitive awards, 2021/22 Student Mentor.
- Courses: Power, analog, and digital electronics, control theory, VLSI, electric drives, RF and microwave systems.

### **PROJECTS**

**Liquid Rocket Chief Engineer,** *U of T Aerospace Team* Jun 2022 – Sep 2023 | Toronto, ON, Canada

- Coordinated the design, analysis, fabrication, and testing of a high-altitude liquid-propellant rocket with 19.25 kNs of total impulse and a C\$35000 budget.
- Created the design requirements, concept of operations, BOMs, and mass budgets for propulsion, avionics, GSE, aerodynamics, airframe, and recovery subsystems.
- Organized a preliminary design review with advisors and communicated the project to 50+ members at onboarding sessions and team meetings.

Avionics Subsystem Lead, U of T Aerospace Team Jun 2021 – May 2022 | Toronto, ON, Canada

- Managed a team to design and integrate buck and boost converters, radio transceivers, GPS, Li-ion batteries, microcontrollers, servo motors, thermocouples, load cells, pressure sensors, and ADCs in the ground and flight systems of an award-winning hybrid rocket. ☑
- Collaborated with propulsion and airframe systems over SolidWorks to ensure avionics hardware meets mechanical requirements (sizes, shapes, clearances, layout, ports, harnesses, mounts, etc.).
- Designed surge-protected relay circuits to control DC motors with a *Raspberry Pi* over a wireless network from a custom C++ GUI, increasing the power rating by 20x.
- Debugged a custom I2C strain gauge amplifier PCB using an oscilloscope, *Arduino*, bench supply, and DMM.

## **Hobby Electronics**

- Built a guitar distortion pedal based on a commonemitter NPN Darlington pair, and a tremolo pedal with true bypass switching using a phase shift oscillator.
- Designed, breadboarded, and debugged an LM317based adjustable linear power supply using KiCad and a DMM, featuring voltage indicator LEDs driven by a Schmitt-triggered LM339 and a resistor ladder.
- Soldered through-hole perfboards and packaged them in custom 3D-printed enclosures created in Fusion 360.